## **Low Inductance Capacitors**

#### Introduction



The signal integrity characteristics of a Power Delivery Network (PDN) are becoming critical aspects of board level and semiconductor package designs due to higher operating frequencies, larger power demands, and the ever shrinking lower and upper voltage limits around low operating voltages. These power system challenges are coming from mainstream designs with operating frequencies of 300MHz or greater, modest ICs with power demand of 15 watts or more, and operating voltages below 3 volts.

The classic PDN topology is comprised of a series of capacitor stages. Figure 1 is an example of this architecture with multiple capacitor stages.

An ideal capacitor can transfer all its stored energy to a load instantly. A real capacitor has parasitics that prevent instantaneous transfer of a capacitor's stored energy. The true nature of a capacitor can be modeled as an RLC equivalent circuit. For most simulation purposes, it is possible to model the characteristics of a real capacitor with one capacitor, one resistor, and one inductor. The RLC values in this model are commonly referred to as equivalent series capacitance (ESC), equivalent series resistance (ESR), and equivalent series inductance (ESL).

The ESL of a capacitor determines the speed of energy transfer to a load. The lower the ESL of a capacitor, the faster that energy can be transferred to a load. Historically, there has been a tradeoff between energy storage (capacitance) and inductance (speed of energy delivery). Low ESL devices typically have low capacitance. Likewise, higher capacitance devices typically have higher ESLs. This tradeoff between ESL (speed of energy delivery) and capacitance (energy storage) drives the PDN design topology that places the fastest low ESL capacitors as close to the load as possible. Low Inductance MLCCs are found on semiconductor packages and on boards as close as possible to the load.

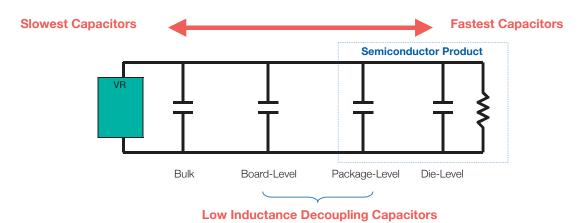


Figure 1 Classic Power Delivery Network (PDN) Architecture

#### LOW INDUCTANCE CHIP CAPACITORS

The key physical characteristic determining equivalent series inductance (ESL) of a capacitor is the size of the current loop it creates. The smaller the current loop, the lower the ESL. A standard surface mount MLCC is rectangular in shape with electrical terminations on its shorter sides. A Low Inductance Chip Capacitor (LICC) sometimes referred to as Reverse Geometry Capacitor (RGC) has its terminations on the longer side of its rectangular shape.

When the distance between terminations is reduced, the size of the current loop is reduced. Since the size of the current loop is the primary driver of inductance, an 0306 with a smaller current loop has significantly lower ESL then an 0603. The reduction in ESL varies by EIA size, however, ESL is typically reduced 60% or more with an LICC versus a standard MLCC.

#### INTERDIGITATED CAPACITORS

The size of a current loop has the greatest impact on the ESL characteristics of a surface mount capacitor. There is a secondary method for decreasing the ESL of a capacitor. This secondary method uses adjacent opposing current loops to reduce ESL. The InterDigitated Capacitor (IDC) utilizes both primary and secondary methods of reducing inductance. The IDC architecture shrinks the distance between terminations to minimize the current loop size, then further reduces inductance by creating adjacent opposing current loops.

An IDC is one single capacitor with an internal structure that has been optimized for low ESL. Similar to standard MLCC versus LICCs, the reduction in ESL varies by EIA case size. Typically, for the same EIA size, an IDC delivers an ESL that is at least 80% lower than an MLCC.



## **Low Inductance Capacitors**

#### Introduction



#### LAND GRID ARRAY (LGA) CAPACITORS

Land Grid Array (LGA) capacitors are based on the first Low ESL MLCC technology created to specifically address the design needs of current day Power Delivery Networks (PDNs). This is the 3rd low inductance capacitor technology developed by AVX. LGA technology provides engineers with new options. The LGA internal structure and manufacturing technology eliminates the historic need for a device to be physically small to create small current loops to minimize inductance.

The first family of LGA products are 2 terminal devices. A 2 terminal 0306 LGA delivers ESL performance that is equal to or better than an 0306 8 terminal IDC. The 2 terminal 0805 LGA delivers ESL performance that approaches the 0508 8 terminal IDC. New designs that would have used 8 terminal IDCs are moving to 2 terminal LGAs because the layout is easier for a 2 terminal device and manufacturing yield is better for a 2 terminal LGA versus an 8 terminal IDC.

LGA technology is also used in a 4 terminal family of products that AVX is sampling and will formerly introduce in 2008. Beyond 2008, there are new multi-terminal LGA product families that will provide even more attractive options for PDN designers.

#### **LOW INDUCTANCE CHIP ARRAYS (LICA®)**

The LICA® product family is the result of a joint development effort between AVX and IBM to develop a high performance MLCC family of decoupling capacitors. LICA was introduced in the 1980s and remains the leading choice of designers in high performance semiconductor packages and high reliability board level decoupling applications.

LICA® products are used in 99.999% uptime semiconductor package applications on both ceramic and organic substrates. The C4 solder ball termination option is the perfect compliment to flip-chip packaging technology. Mainframe class CPUs, ultimate performance multi-chip modules, and communications systems that must have the reliability of 5 9's use LICA®.

LICA® products with either Sn/Pb or Pb-free solder balls are used for decoupling in high reliability military and aerospace applications. These LICA® devices are used for decoupling of large pin count FPGAs, ASICs, CPUs, and other high power ICs with low operating voltages.

When high reliability decoupling applications require the very lowest ESL capacitors, LICA® products are the best option.

#### 470 nF 0306 Impedance Comparison

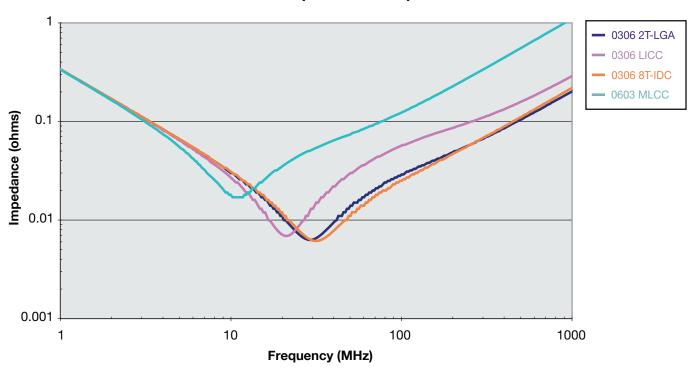


Figure 2 MLCC, LICC, IDC, and LGA technologies deliver different levels of equivalent series inductance (ESL).



# **Low Inductance Ceramic Capacitors**



#### LICC (Low Inductance Chip Capacitors) 0306/0508/0612 RoHS Compliant

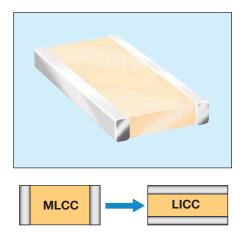
#### **GENERAL DESCRIPTION**

The key physical characteristic determining equivalent series inductance (ESL) of a capacitor is the size of the current loop it creates. The smaller the current loop, the lower the ESL.

A standard surface mount MLCC is rectangular in shape with electrical terminations on its shorter sides. A Low Inductance Chip Capacitor (LICC) sometimes referred to as Reverse Geometry Capacitor (RGC) has its terminations on the longer sides of its rectangular shape. The image on the right shows the termination differences between an MLCC and an LICC.

When the distance between terminations is reduced, the size of the current loop is reduced. Since the size of the current loop is the primary driver of inductance, an 0306 with a smaller current loop has significantly lower ESL then an 0603. The reduction in ESL varies by EIA size, however, ESL is typically reduced 60% or more with an LICC versus a standard MLCC.

AVX LICC products are available with a lead-free finish of plated Nickel/Tin.

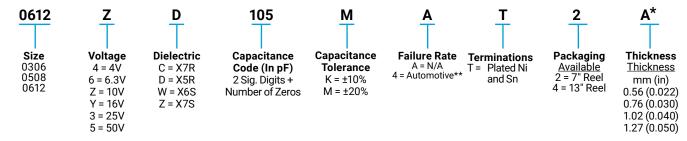


#### PERFORMANCE CHARACTERISTICS

	·		
Capacitance Tolerances	K = ±10%; M = ±20%		
Operation Temperature Range	X7R = -55°C to +125°C X5R = -55°C to +85°C X7S = -55°C to +125°C		
<b>Temperature Coefficient</b> X7R, X5R = $\pm 15\%$ ; X7S = $\pm 22\%$			
Voltage Ratings	4, 6.3, 10, 16, 25 VDC		
Dissipation Factor	4V, 6.3V = 6.5% max; 10V = 5.0% max 16V = 3.5% max; 25V = 3.0% max		
Insulation Resistance (@+25°C, RVDC)	100,000MΩ min, or 1,000MΩ per $\mu F$ min.,whichever is less		



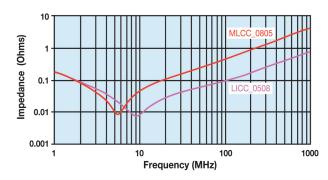
#### **HOW TO ORDER**

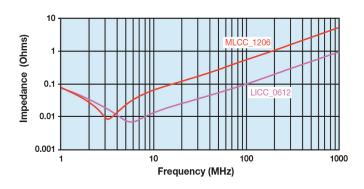


<sup>\*</sup>See the thickness tables on the next page.

NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers.

#### TYPICAL IMPEDANCE CHARACTERISTICS







<sup>\*\*</sup>Select voltages for Automotive version, contact factory

# **Low Inductance Ceramic Capacitors**



# LICC (Low Inductance Chip Capacitors) 0306/0508/0612 RoHS Compliant

S	SIZE			0306	5			(	0508	3				0612	2	
Pac	kaging	Embossed			Embossed				Embossed							
Length	mm (in.)		0.81 + 0.15 (0.032 ± 0.006)			1.27 + 0.25 (0.050 ± 0.010)				1.60 + 0.25 (0.063 ± 0.010)						
Width	mm (in.)			50 + 0. 53 ± 0.				2.00 + 0.25 (0.080 ± 0.010)				3.20 + 0.25 (0.126 ± 0.010)				
Cap Code	WVDC	4	6.3	10	16	25	6.3	10	16	25	50	6.3	10	16	25	50
102	Cap 0.001		Α	Α	Α	Α	S	S	S	S	V	S	S	S	S	V
222	(μF) .0022		Α	Α	Α	Α	S	S	S	S	٧	S	S	S	S	٧
332	0.0033		Α	Α	Α	Α	S	S	S	S	٧	S	S	S	S	٧
472	0.0047		Α	Α	Α	Α	S	S	S	S	٧	S	S	S	S	٧
682	0.0068		Α	Α	Α	Α	S	S	S	S	٧	S	S	S	S	٧
103	0.01		Α	Α	Α	Α	S	S	S	S	٧	S	S	S	S	٧
153	0.015		Α	Α	Α	Α	S	S	S	S	٧	S	S	S	S	W
223	0.022		Α	Α	Α	Α	S	S	S	S	٧	S	S	S	S	W
333	0.033		Α	Α	Α		S	S	S	٧	٧	S	S	S	S	W
473	0.047		Α	Α	Α		S	S	S	٧	Α	S	S	S	S	W
683	0.068		Α	Α	Α		S	S	S	Α	Α	S	S	S	٧	W
104	0.1		Α	Α	M		S	S	٧	Α	Α	S	S	S	٧	W
154	0.15		Α	Α			S	S	٧			S	S	S	W	W
224	0.22		Α	Α			S	S	Α			S	S	٧	W	
334	0.33						٧	٧	Α			S	S	٧		
474	0.47						٧	٧	///			S	S	٧		
684	0.68						Α	Α				V	٧	W		
105	1	A					Α	Α				V	٧	Α		
155	1.5						/					W	W			
225	2.2											Α	Α			
335	3.3				İ							//			İ	
475	4.7															
685	6.8															
106	10															

Solid = X7R







mm (in.)

0306

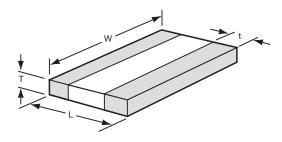
Code Thickness

A 0.56 (0.022)

mm (in.)						
0508						
Code	Thickness					
S	0.56 (0.022)					
V	0.76 (0.030)					
Α	1.02 (0.040)					

	mm (in.)				
0612					
Code	Thickness				
S	0.56 (0.022)				
V	0.76 (0.030)				
W	1.02 (0.040)				
Α	1.27 (0.050)				

# PHYSICAL DIMENSIONS AND PAD LAYOUT



#### **PHYSICAL DIMENSIONS**

mm (in.)

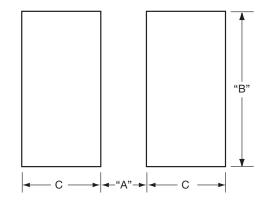
Size	L	W	t
0206	0.81 ± 0.15	1.60 ± 0.15	0.13 min.
0306	$(0.032 \pm 0.006)$	$(0.063 \pm 0.006)$	(0.005 min.)
0E00	1.27 ± 0.25	2.00 ± 0.25	0.13 min.
0508	$(0.050 \pm 0.010)$	$(0.080 \pm 0.010)$	(0.005 min.)
0612	1.60 ± 0.25	3.20 ± 0.25	0.13 min.
0012	(0.063 ± 0.010)	(0.126 ± 0.010)	(0.005 min.)

T - See Range Chart for Thickness and Codes

#### **PAD LAYOUT DIMENSIONS**

mm (in.)

			111111 (111.)
Size	Α	С	
0306	0.31 (0.012)	1.52 (0.060)	0.51 (0.020)
0508	0.51 (0.020)	2.03 (0.080)	0.76 (0.030)
0612	0.76 (0.030)	3.05 (0.120)	0.635 (0.025)





# **Mouser Electronics**

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#### AVX:

0306YC103KAT2A 0306YC103MAT2A 0306YC153KAT2A 0306YC223KAT2A 0306YC473KAT2A 0306YC683KAT2A 0306YD104KAT2A 0306ZC103KAT2A 0306ZC103MAT2A 0306ZC104KAT2A 0306ZC153KAT2A 0306ZC223KAT2A 0306ZC224KAT2A 0306ZC224MAT2A 0306ZC224MAT4A 0306ZC473KAT2A 0306ZC683KAT2A 05083C103KAT2S 05083C103MAT2A 05083C103MAT2W 05083C104KAT2A 05083C104KAT2W 05083C104MAT2A 05083C223KAT2A 05083C223KAT2S 05083C223MAT2A 05083C473KAT2V 05083C683KAT2A 05085C103MAT2A 05085C104KAT2A 05086C103KAT2S 05086C474KAT2V 05086C684KAT2A 05086D105KAT2A 05086D105MAT2A 05086D155KAT2A 0508YC103KAT2A 0508YC103KAT2S 0508YC104KAT2W 0508YC184KAT2V 0508YC224KAT2A 0508YC274KAT2A 0508ZC103KAT2A 0508ZD105KAT2A 0508ZD105MAT2A 0508ZD105MAT4A 06123C103KAT2A 06123C104KAT2A 06123C104KAT2V 06123C104MAT2A 06123C154KAT2W 06123C222KAT2V 06123C224KAT2A 06123C224KAT2W 06123C473KAT2S 06123C473MAT4U 06125C103KAT2A 06125C104MAT2A 06126C103KAT2S 06126C104KAT2S 06126C105KAT2V 06126D225KAT2A 06126D335KAT2A 06126D335MAT2A 0612ZD225KAT2A 0612YC103KAT2S 0612YC104KAT2S 0612YC104KAT2V 0612YC104KAT4V 0612YC104MAT2A 0612YC105KAT2A 0612YC105MAT2A 0612YC224KAT2V 0612YC224MAT2A 0612YC473KAT2S 0612YC474KAT2V 0612YC474MAT2A 0612YC684KAT2W 0612ZC103KAT2S 0612ZC104KAT2A 0612ZC104KAT2S 0612ZC105KAT2A 0612ZC105KAT2V 0612ZC105MAT2A 0612ZC105MAT2W 0612ZC223KAT2S 0612ZC225KAT2A 0612ZC474KAT2S 0612ZC474MAT2A